

NH-4000A Series ACF Laminating System (formerly known as MACFL)

Designed for fine-pitch, ACF bonding applications (> 30 microns), the ACF (Anisotropic Conductive Film) Laminator uses a two or three-step process to connect materials such as flex-foil to glass or flex-foil to PCB. ACF Laminating/Pre-Bonding is achieved by dispensing and cutting the ACF tape, positioning it over the surface of the parts to be bonded, and moving the thermode into position. The flex is then moved into position to align the traces to the substrate, and the thermode is actuated to complete the bond.

Key Features NH-4000 Series ACF Laminating System

- > Compact and flexible systems for high quality connections
- > Connecting displays to PCB, bonding glass panel displays and flex foils
- > User friendly system configuration, including optional plug & play modules
- > Integrated Constant Heat process control based on proven technology
- > Ideal price-performance (throughput) ratio
- > CE approved
- > Pneumatic bond head, X-Y Hot Bar planarity adjustment and electronic system control included

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OUR TECHNOLOGIES



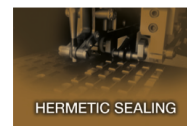
RESISTANCE WELDING



LASER WELDING



LASER MARKING



HERMETIC SEALING



HOT BAR REFLOW
SOLDERING & BONDING



SYSTEMS SOLUTIONS

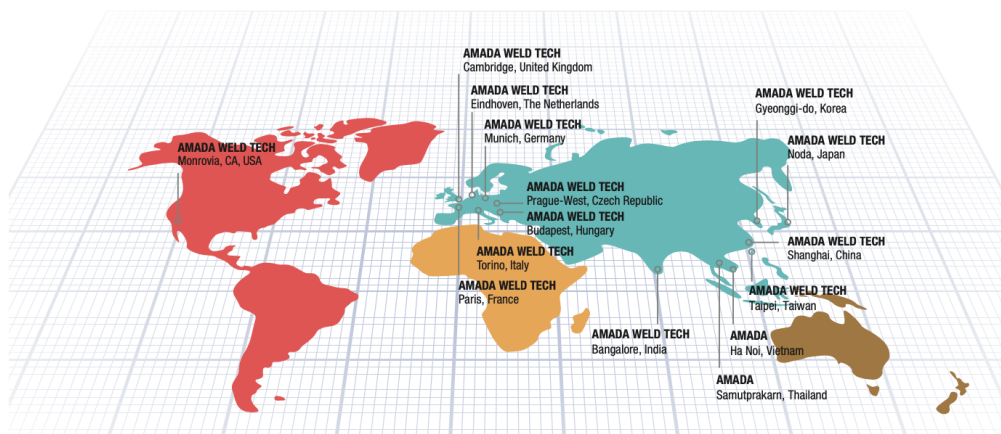


LASER CUTTING



MICRO TIG WELDING

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